



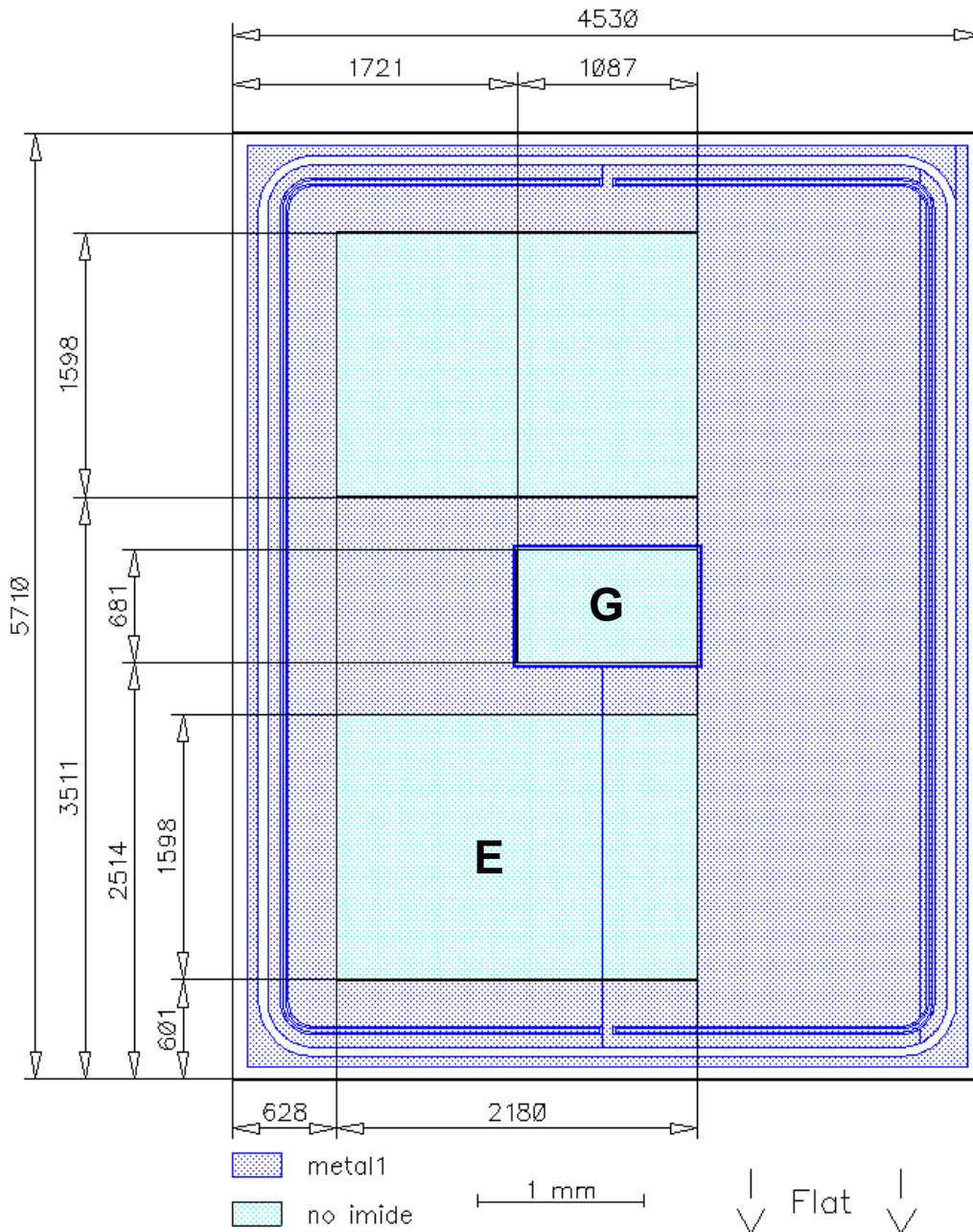
SIGC25T120C

Further Electrical Characteristic

Switching characteristics and thermal properties are depending strongly on module design and mounting technology and can therefore not be specified for a bare die.

Chip Drawing

Die-Size 4530 um x 5710 um



E = Emitter pad
G = Gate pad